

Filename: PMP7118REVA_bom.xls						
Date: 03/12/2012						
<b>PMP7118REVA BOM</b>						
COUNT	RefDes	Value	Description	Size	Part Number	MFR
2	C1	1500uF	Capacitor, Electrolythic, 35V, 1.8A, 35milliOhm	0.670 x 0.698 inch	EEVFK1V152M (J16)	Panasonic
	C2	1500uF	Capacitor, Electrolythic, 35V, 1.8A, 35milliOhm	0.670 x 0.698 inch	EEVFK1V152M (J16)	Panasonic
4	C3	4.7uF	Capacitor, Ceramic, 50V, X7R, 15%	1210	C3225X7R1H475M	TDK
	C4	4.7uF	Capacitor, Ceramic, 50V, X7R, 15%	1210	C3225X7R1H475M	TDK
	C5	4.7uF	Capacitor, Ceramic, 50V, X7R, 15%	1210	C3225X7R1H475M	TDK
	C6	4.7uF	Capacitor, Ceramic, 50V, X7R, 15%	1210	C3225X7R1H475M	TDK
1	C7	2.2nF	Capacitor, Ceramic, 100V, X7R, 15%	0805	std	std
4	C8	2.2uF	Capacitor, Ceramic, 100V, X7R, 15%	1210	C3225X7R2A225M	TDK
	C9	2.2uF	Capacitor, Ceramic, 100V, X7R, 15%	1210	C3225X7R2A225M	TDK
2	C10	470uF	Capacitor, Electrolythic, 63V, 1.41A, 82milliOhm	0.670 x 0.698 inch	EEVFK1J471M (J16)	Panasonic
1	C11	100nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	std	std
	C12	2.2uF	Capacitor, Ceramic, 100V, X7R, 15%	1210	C3225X7R2A225M	TDK
	C13	2.2uF	Capacitor, Ceramic, 100V, X7R, 15%	1210	C3225X7R2A225M	TDK
	C14	470uF	Capacitor, Electrolythic, 63V, 1.41A, 82milliOhm	0.670 x 0.698 inch	EEVFK1J471M (J16)	Panasonic
2	C15	1uF	Capacitor, Ceramic, 16V, X7R, 15%	0603	C1608X7R1C105M	TDK
1	C16	470pF	Capacitor, Ceramic, 50V, NPO, 5%	0603	std	std
1	C17	27nF	Capacitor, Ceramic, 50V, X7R, [tol]	0603	std	std
	C18	1uF	Capacitor, Ceramic, 16V, X7R, 15%	0603	C1608X7R1C105M	TDK
1	C19	330pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	std	std
1	C20	68pF	Capacitor, Ceramic, 50V, NPO, [tol]	0603	std	std
1	D1	MBR2060CT	Diode, Dual Schottky, 20A, 60V	TO220	MBR2080CT	IR / ONsemi
2	HS1	SK 437 35 STC 2	Heatsink, TO-220/218 veritcal, Rth 18K/W	0.640 x 0.640 inch	SK 437 35 STC 2 and THF 409 220 2	Fischer Elektronik
	HS2	SK 437 35 STC 2	Heatsink, TO-220/218 veritcal, Rth 18K/W	0.640 x 0.640 inch	SK 437 35 STC 2 and THF 409 220 2	Fischer Elektronik
2	J1	D120/2DS	Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35 inch	D120/2DS	OST
	J2	D120/2DS	Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35 inch	D120/2DS	OST
1	L1	15uH	Inductor, SMT Power, 18Asat, 2.86 milliohm	1.100 x 1.100 inch	SER2918H-153KL	Coilcraft
1	Q1	MMBT2222A	TRANSISTOR, NPN, HIGH-PERFORMANCE, 500mA	SOT-23	MMBT2222A	Fairchild
1	Q2	CSD18533KCS	MOSFET, N-ch, 60-V, 4.9-milliOhms, 21.7nC	TO-220V	CSD18533KCS	TI
1	Q3	MMBT2907ALT1	Transistor, PNP, -60V, -600mA, 225-W	SOT23	MMBT2907ALT1	On Semi
1	R1	4.7	Resistor, Chip, 1/16W, 1%	0603	std	std
1	R2	392k	Resistor, Chip, 1/16W, 1%	0603	std	std
1	R3	2.2	Resistor, Chip, 1/2W, 5%	2010	Std	Std
1	R4	1k	Resistor, Chip, 1/16W, 1%	0603	std	std
1	R5	0.005	Resistor, Chip, 1/2W, 5%	2010	Std	Std
1	R6	137k	Resistor, Chip, 1/16W, 1%	0603	std	std

1	R7	137k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R8	49.9	Resistor, Chip, 1/16W, 1%	0603	std	std
1	R9	2k	Resistor, Chip, 1/16W, 0.1%	0603	TNPW0603xxxxBT9	Vishay
1	R10	27.4	Resistor, Chip, 1/16W, 0.1%	0603	TNPW0603xxxxBT9	Vishay
3	TP1	5010	Test Point, Red, Thru Hole	0.125 x 0.125 inch	5010	Keystone
2	TP2	5011	Test Point, Black, Thru Hole	0.125 x 0.125 inch	5011	Keystone
1	TP3	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
	TP4	5010	Test Point, Red, Thru Hole	0.125 x 0.125 inch	5010	Keystone
	TP5	5010	Test Point, Red, Thru Hole	0.125 x 0.125 inch	5010	Keystone
	TP6	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 inch	5002	Keystone
3	TP7	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 inch	5002	Keystone
	TP8	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 inch	5002	Keystone
	TP9	5011	Test Point, Black, Thru Hole	0.125 x 0.125 inch	5011	Keystone
1	U1	TPS40210DGQ	IC, 4.5V-52V I/P, Current Mode Boost Controller	DGQ10	TPS40210DGQ	TI
Notes:	1. These assemblies are ESD sensitive, ESD precautions shall be observed.					
	2. These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.					
	3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.					
	4. Ref designators marked with an asterisk (***) cannot be substituted.					
	All other components can be substituted with equivalent MFG's components.					

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